

Title (en)
ASSEMBLY COMPRISING AN AUXILIARY ADHESIVE DISPENSING DEVICE

Title (de)
ANORDNUNG MIT EINER DISPENSHILFSVORRICHTUNG

Title (fr)
ARRANGEMENT AVEC UN DISPOSITIF DISTRIBUTEUR D'ADHÉSIF AUXILIAIRE

Publication
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Application
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Abstract (en)
An embodiment of the present invention provides an auxiliary adhesive dispensing apparatus, where the auxiliary adhesive dispensing apparatus is connected to a PCB board through an opening on a side surface of a shielding cover above the PCB board, and the auxiliary adhesive dispensing apparatus includes: a flow guiding groove, an adhesive-injection opening connected to an end of the flow guiding groove, and a fixing part connecting the flow guiding groove and the PCB board. The auxiliary adhesive dispensing apparatus provided in this embodiment of the present invention is connected to a PCB board through an opening on a side surface of a shielding cover above the PCB board. By means of the auxiliary adhesive dispensing apparatus, an adhesive dispensing operation can still be performed after a shielding cover is mounted, so that the adhesive dispensing operation can be performed after second-reflow soldering processing. By means of the auxiliary adhesive dispensing apparatus, an adhesive dispensing operation is completed after second reflow soldering, and there is no more second reflow soldering after adhesive dispensing is complete, which can reduce risks of tin whisker bridging in a chip at which adhesive dispensing is performed and tin balls at a peripheral chip.

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